POLYMER AM AT THE KANSAS CITY NATIONAL SECURITY CAMPUS (KCNSC)

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The Department of Energy's Kansas City National Security Campus is operated and managed by Honeywell Federal Manufacturing & Technologies, LLC under contract number DE-NA0002839 Principal R&D Scientist – Materials Center of Excellence Leader University of Southern Mississippi (Ph.D. polymer science & engineering) St. Norbert College (BS chemistry)



KCNSC: 2013 – present ORNL: 2004 – 2013

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KANSAS CITY NATIONAL SECURITY CAMPUS

One Mission One Ecosystem Multiple Locations



Quick View

- A multi-mission engineering and manufacturing enterprise delivering trusted national security products and government services
- Department of Energy leased facility
- DOE National Nuclear Security Administration
 (NNSA) and DOE-IN oversight
- Managed & operated by Honeywell
- 5300+ employees
- \$1.6B annual federal budget

Locations

- Botts Campus: 1.5M sq. ft. in 4 main buildings, including a 350K sq. ft. SCIF (Buildings 1–4)
- KCNSC South (Building 20)
- KCNSC West (Building 21)
- KCNSC North (Building 22)
- KCNSC East (Building 23)
- Albuquerque, NM: offices, 130k sq. ft. fabrication shop and vehicle depot facility

OUR MISSION

To support national security objectives by providing exceptional solutions, managed operations and targeted services through talented people.



NNSA MISSION PRIORITIES

STOCKPILE STEWARDSHIP

OUTLINE

Background on Polymer AM at KCNSC

- A look back and early successes
- Approach to science-based manufacturing
- Polymer AM Consortium

Highlight research findings in the following areas:

- High-temperature SLS development
- Performance improvements in thermoplastics for FDM
- Tunable silicone systems for DIW
- Rigid Syntactic Replacements
- "Smart" Materials for DIW

Conventional Polymer Manufacturing Issues

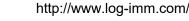
- Challenging to change product design...
 - Costly infrastructure (e.g., molds) and space needs
 - Scale-up from benchtop to large production
 - Some geometries are not accessible (topology optimization)
- Choice of polymeric materials
 - Limited selection of materials: conventional materials ≠ polymer AM materials
 - Current materials designed for current manufacturing processes (IM)
 - AM market is still small custom materials development needed
- Advantages offered by AM over conventional methods:
 - Improved economics: less waste, reduced cost, reduced time to market, etc.
 - Mass customization: small #s of precision parts
 - High-strength structures (improved product quality)



Conventional injection molding equipment









Need to Focus on Processes AND Materials



• Most 3D printing companies build printers and then try to adapt materials to fit those printers.

• Materials and machines can be tailored to meet the needs of the NSE.



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POLYMER AM THEN & NOW

Then FY14

Number of machines - 40+ (35 MakerBots)

- Mostly desktop FDM systems, initial 3-axis DIW, "old-school" SLA systems...
- Procured 35 printers in FY14 and 'they are not only changing the Paradigm, but saved another \$6.4M in the first part of FY14 printing over 5,000 development parts, tools, and fixtures."

Number of printable polymers available ~ 20

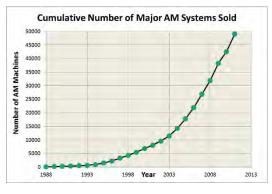
- Discussions with polymer suppliers (e.g., Bayer Material Sciences/Covestro) at ACS National Meeting – "no real market for polymer AM"
- Number of insertions
 - What was inserted/numbers of parts, etc. W88Alt 370 Pads
- Primary use: tooling & fixtures, prototypes
- **Technical Successes**
 - Changed way of thinking about manufacturing,
 - Started to think about using topology optimization ٠
 - Realization that DIW silicone pads could be modelled (compared to ٠ stochastic foams - CS/RTV), ability to guickly make visual displays/prototypes



MakerBot Replicator 2X



Stratasys Fortus 900mc installed February 2014



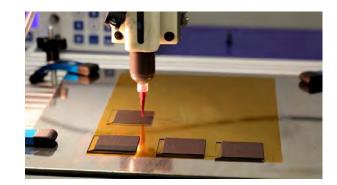
Source: Wohlers Report 2012



POLYMER AM THEN & NOW

Now FY19/FY20

- Number of machines 60+
 - R&D efforts and printers at university collaborators
 - Multiple 5-axis DIW systems in production (M-90) and R&D
- Number of printable polymers available > 100
- Primary use: WR product, mocks, fixtures, prototypes, initial mold designs
- Technical Successes
 - Polymer AM Consortium, AM facility, ACE facility, multi-site ACT project (AM Thermosets), improved understanding of process-structure-property relationships (science-based mfg), materials development with vendors (Solvay, ALM), custom formulations
- Technical Opportunities
 - Accelerated aging/compatibility
- What's around the corner?
 - Microstereolithography, foams, thermosets/rigid syntactics, custom AM feedstock facility (filaments and powders), multi-functional materials/sensors



Direct Ink Writing of novel inks



High-temperature SLS capabilities: Prodways HT2000 at Virginia Tech (left) and EOS-NA P400 at KCNSC (right)



POLYMER AM FACILITY (DEPARTMENT M-90)



KCNSC's Science Based Manufacturing Approach

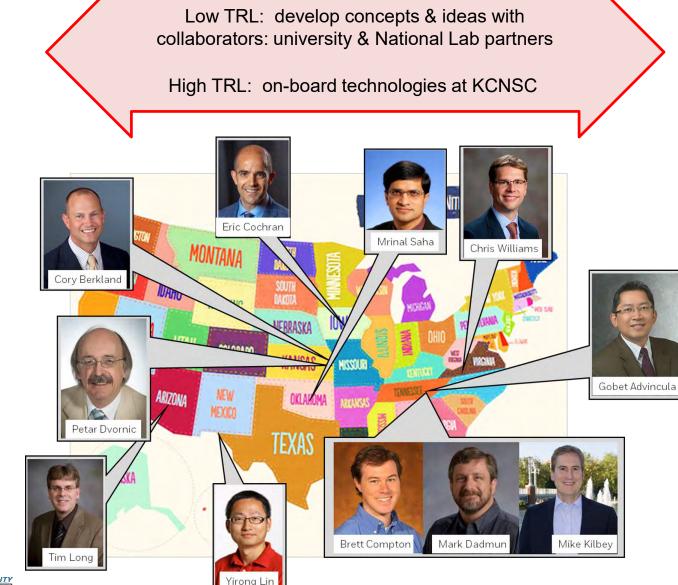
Internal

Fundamental & applied R&D, deployment/insertion

Consortium

Polymer AM

Academic Partners





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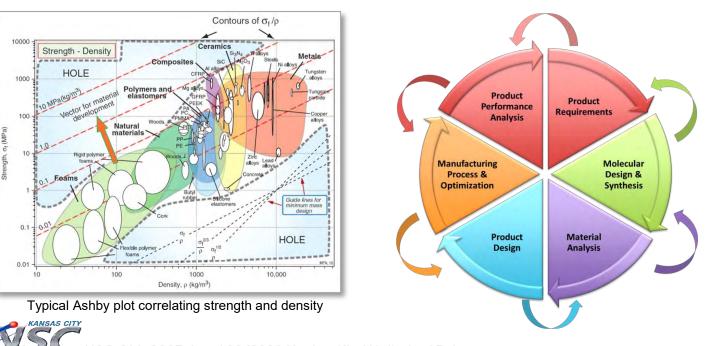


External

Fundamental/basic R&D

Polymer AM Consortium Goals

- Fundamental understanding of AM processes
 - Develop science-based approach to materials development and machine parameter selection: improve materials, AM processes, and enhance critical material properties to improve processing, performance, lifetime (aging), and safety
- Develop a catalog of the "right" materials for use in NNSA applications
 - Currently available commercial materials are "repurposed" originally designed for traditional manufacturing methods (e.g., injection molding)
- Create a pipeline of talent hire next-generation of scientists/engineers

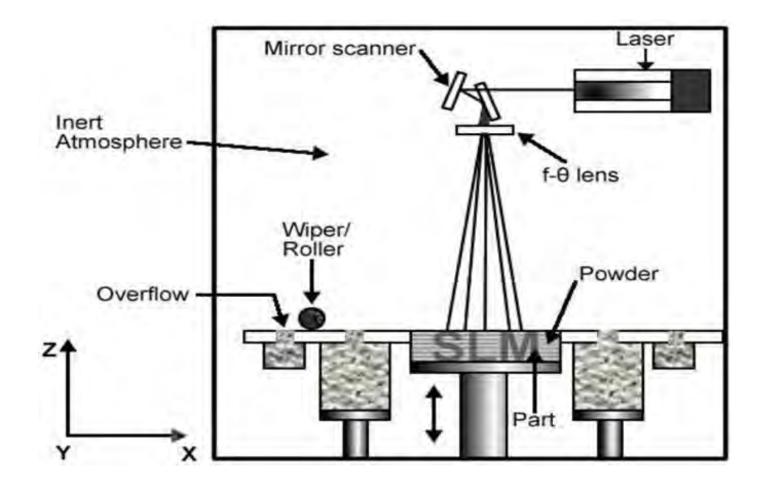


Opportunity to realize breakthrough products via **concurrent design** of **polymer chemistry**, **part geometry**, and **manufacturing process**

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Selective Laser Sintering (SLS)

Technology Overview

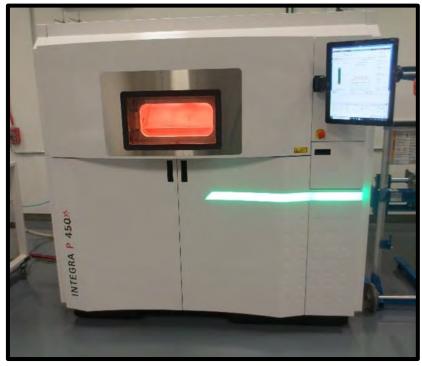








SLS Equipment/Capabilities



EOS P450 Series, High Temp Capable, KCNSC

Other Machines:

- Prodways HT2000 Virginia Tech
- DTM Sinterstation 2500+ Virginia Tech
- Custom Benchtop System University of Oklahoma
- EOS P110 KCNSC





https://natubots.com/vit-sls/?lang=en



https://www.sinterit.com/sinterit-lisa-pro/



VIT/Sinterit Open Source Benchtop Systems, University Partners



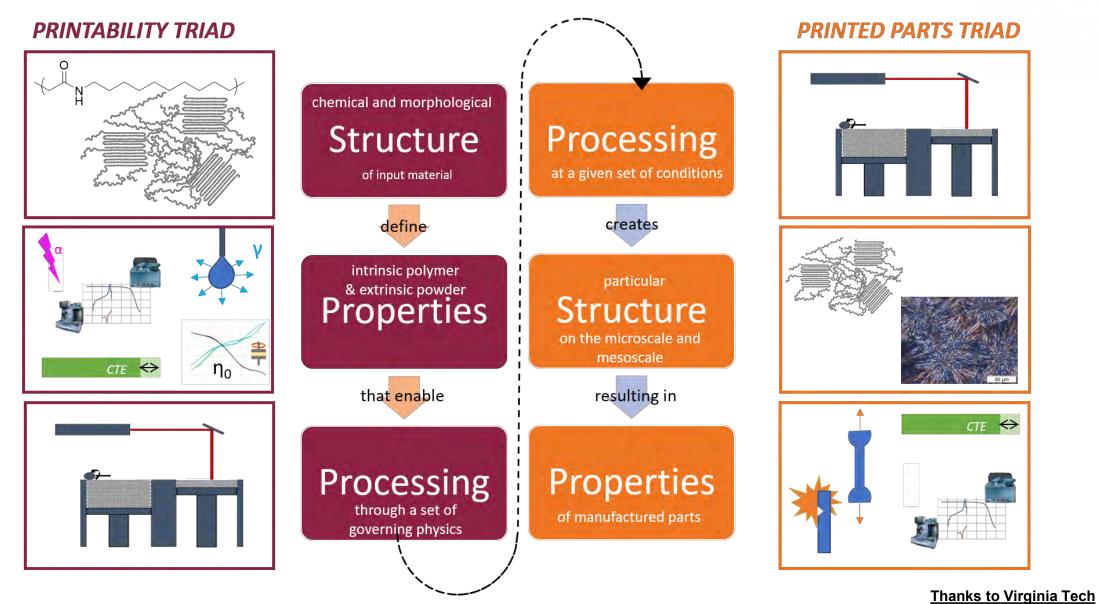
Pallmann Industries Cryomill, KCNSC

https://www.eos.info/en/additive-manufacturing/3d-printing-plastic/eos-polymer-systems/eos-p-396

EOS P395/P396, PA12 Workhorse, KCNSC



Science-Based Manufacturing for SLS



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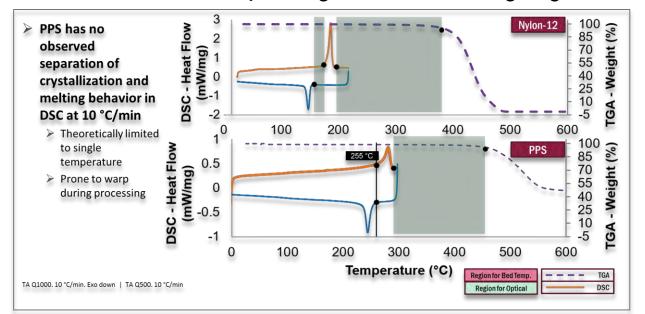
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RAPID DEVELOPMENT OF THE "RIGHT" MATERIALS FOR 3D PRINTING Establishing fundamental understanding of thermal prop

Target application: potting shells & dams

- Material that surrounds electrical connections that is "set in place" with polyurethane potting compounds
- Currently made via injection molding
- Strong desire to move to a science-based manufacturing approach: understand structureproperty-process relationships
- Worked with supplier (Solvay) to get correct MW, particle size, etc.

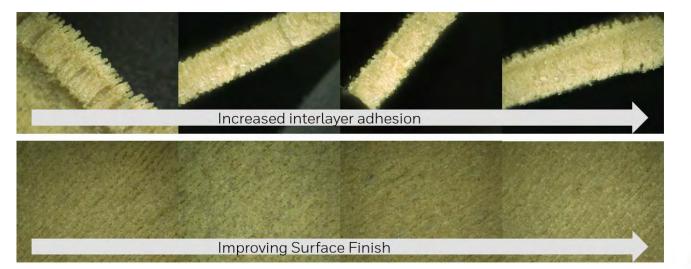
Establishing fundamental understanding of thermal properties (PA-12 vs. PPS) for printing – Stable Sintering Region:





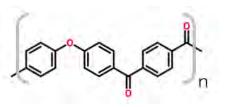
3D PRINTING OF PAEKS AND PEI

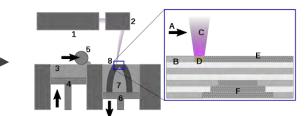
- Why Poly Aryl Ether Ketones (PAEKs)?
 - Desirable dielectric properties
 - Excellent chemical resistance
 - Excellent thermal properties
- Selective Laser Sintering of Poly(Ether Ketone Ketone) PEKK
 - Utilize high-temp SLS system, the EOS Integra P450
 - Prints successful on first attempt utilized methodology developed to intuitively select parameters based on polymeric structure



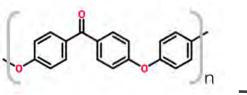
The combination of build temperature, hatch laser power, and contour laser power is important to optimize both interlayer adhesion and part finish.



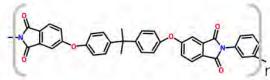




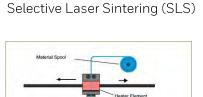
PEKK Chemical Structure

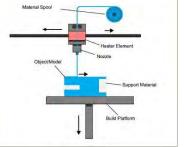


PEEK Chemical Structure



PEI Chemical Structure

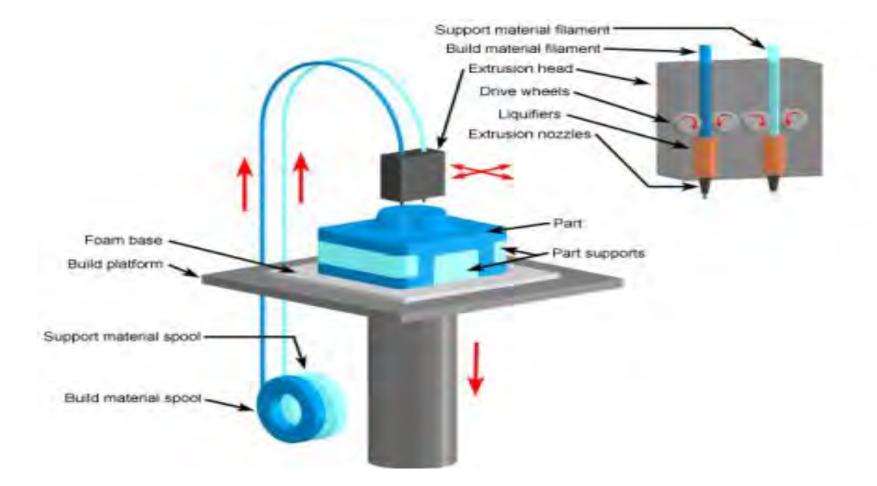




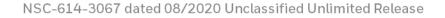
Fused Deposition Modeling (FDM)

Fused Filament Fabrication (FFF)

Technology Overview









FDM Equipment/Capabilities



https://www.aon3d.com/aon-m2-2020-industrial-3d-printer/

AON-M2 HT Capable, Open Source, KCNSC

Other Machines:

- Makerbots
- Lulzbot University of Tennessee Knoxville
- Custom benchtop systems OU, Virginia Tech
- Filabot multiple universities





https://dyzedesign.com/pulsar-pellet-extruder/

Dyze Designs Pellet Extruder, KCNSC



Intamsys Funmat HT, Benchtop, KCNSC & University Partners



https://www.thermofisher.com/order/catalog/product/567-7600#/567-7600

Thermo Scientific Process 11 Twin Screw Extruder, KCNSC



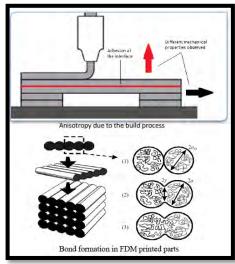
https://www.stratasys.com/3d-printers/fortus-380mc-450mc

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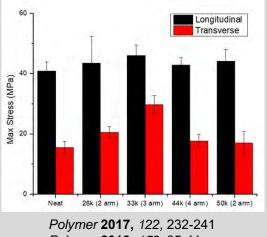
Fortus 450mc, KCNSC



Improving Isotropy Through a Low Molecular Weight Surface Segregating Additive for FDM



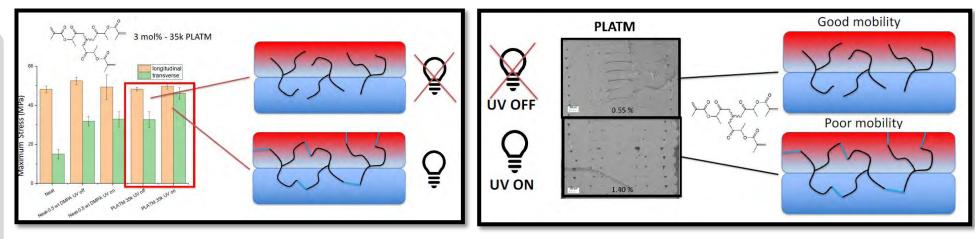
Mechanical properties in transverse (red) and longitudinal (black) orientations



Polymer **2018**, *152*, 35-41



- Aiding inter-filament bonding via molecular assembly
- Small polymer chains diffuse faster than large chains
- Entropically driven to the interface
- Increased inter-filament diffusion and stronger interfaces
- Target MW \rightarrow Greater the M_e, less than majority filament
- Create bimodal blends
 - Low molecular weights (LMW), loadings, chain architectures



Interfacial Adhesic

ow Molecular Weight Species

- UV initiator + LMW additives enables inter-filament crosslinks
- Key to find balance between improved crosslinking and limitation of chain mobility (UV intensity) – reduction of void size

Thanks to the University of Tennessee

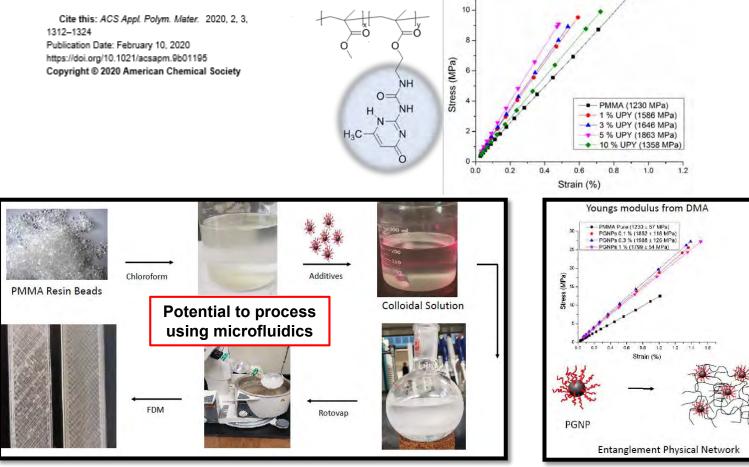


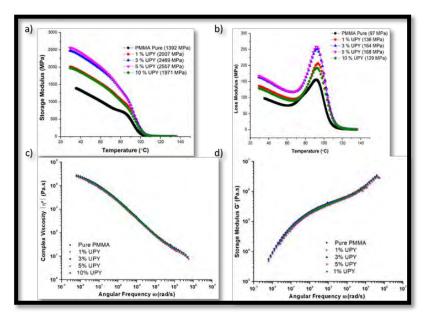
Improved Interfacial Adhesion

Hydrogen-bonding Motifs Attached to Nanoparticle Fillers Dramatically Enhance Mechanical Properties

Tailoring Interfacial Interactions via Polymer-Grafted Nanoparticles Improves Performance of Parts Created by 3D Printing

Dayton P. Street, Adeline Huizhen Mah, William K. Ledford, Steven Patterson, James A. Bergman, Bradley S. Lokitz, Deanna L. Pickel, Jamie M. Messman, Gila E. Stein, and S. Michael Kilbey II*





Small incorporation of H-bonding group (UPY) onto nanoparticles results in mechanically stronger parts while not affecting rheology/processing.

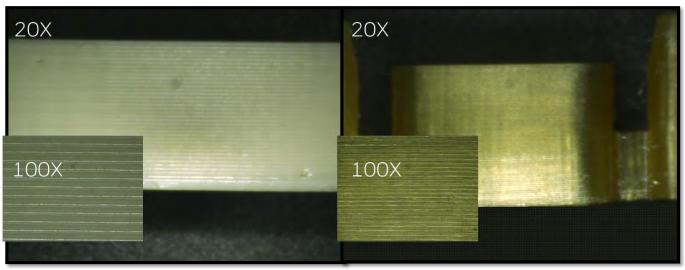
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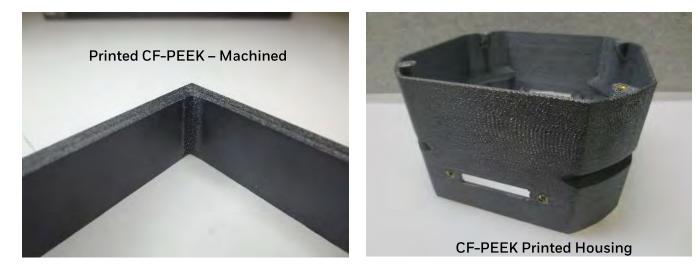
3D PRINTING OF PEEK/ULTEM USING AON-M2 PRINTER



PEEK- 0.2 mm layer heights Ultem 101



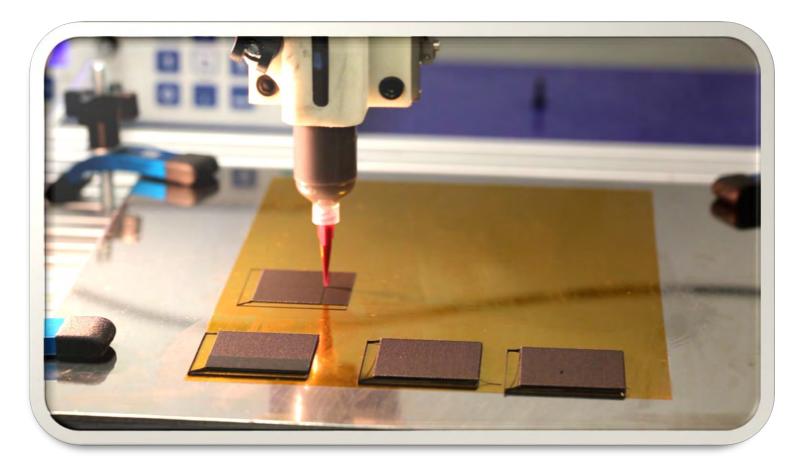




- System has successfully printed PEEK and ULTEM 1010 amongst a variety of other engineering plastics (ABS, ASA, PC, etc.)
- PEEK and carbon fiber-filled PEEK parameter development is ongoing

DIRECT INK WRITE (DIW)

Technology Overview



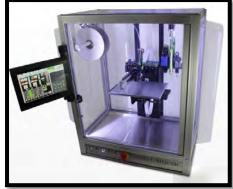
DIW EQUIPMENT/CAPABILITIES



Aerotech 5-Axis Machines, KCNSC



https://www.viscotec-america.com/industryapplications/3d-printing Viscotec Print Heads, KCNSC



http://www.hyrel3d.com/portfolio/system-30m/ Hyrel System 30M, KCNSC

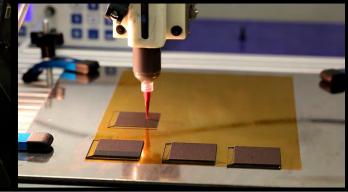


ShopBot 3-Axis Benchtop, KCNSC

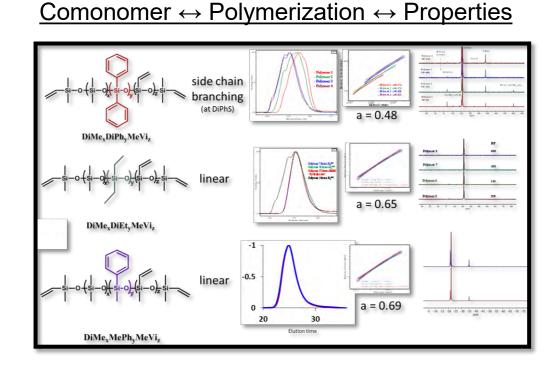
NSC-614-3067 dated 08/2020 Unclassified Unlimited Release



Aerotech 3-Axis Production Machine, 4x Print Head/Substrate, KCNSC



Silicone DIW Resins: Polymer Structure Influences Processing & Aging



- DiPhS incorporation is more difficult to control polymerization
- DiPhS leads to branched polymer structure and is more difficult to compound (high MW)
- DiPhS very electrophilic Si center is more prone to side reactions (chemically binds to silica fillers)

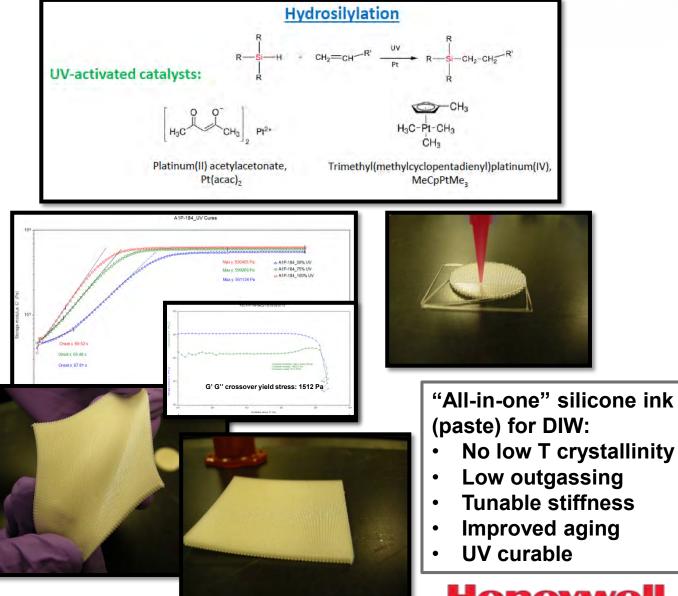
Macromolecules, 2017, 50, 3532; 2018, 51, 895.

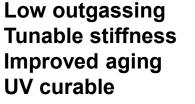
Thanks to Pittsburg State University





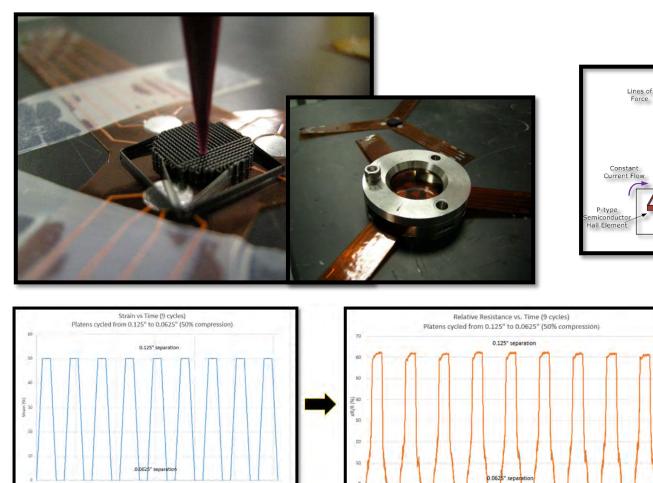
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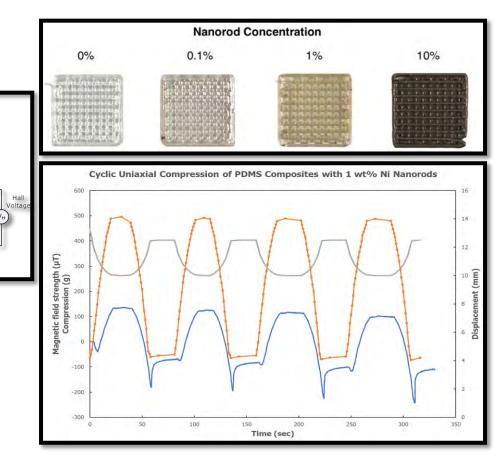


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"SMART" DIW SILICONE PADS



Carbon-based fillers can impart piezoresistive functionality to DIW silicones with little impact on rheology



Ferromagnetic fillers provide the ability to detect changes in magnetic field when a printed part is under stress or strain "wirelessly" via Hall Effect Sensor (triple-axis magnetometer)

Thanks to the University of Kansas

Thanks to the University of Oklahoma

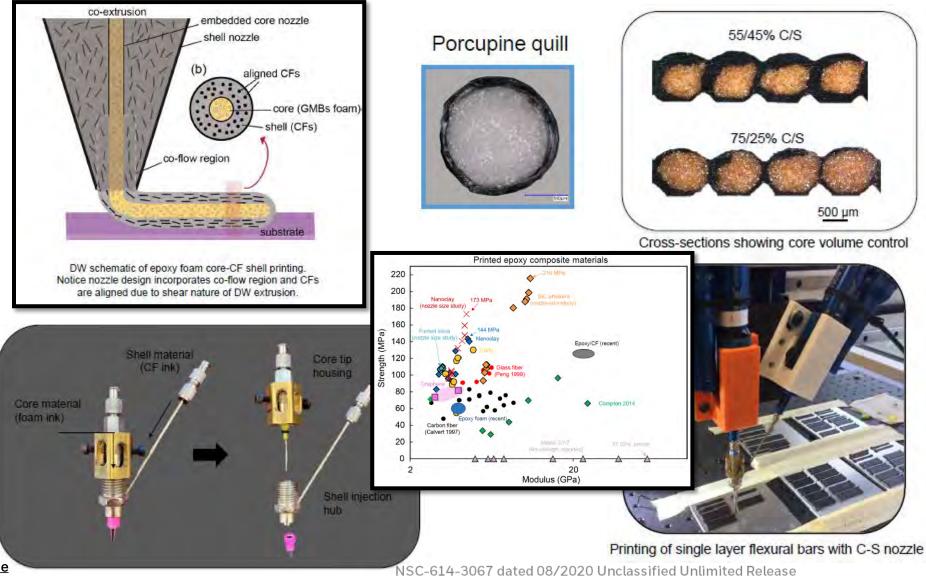
Directional Magnetic Field (H)

•••

DC SI

Thermoset Foams via DIW

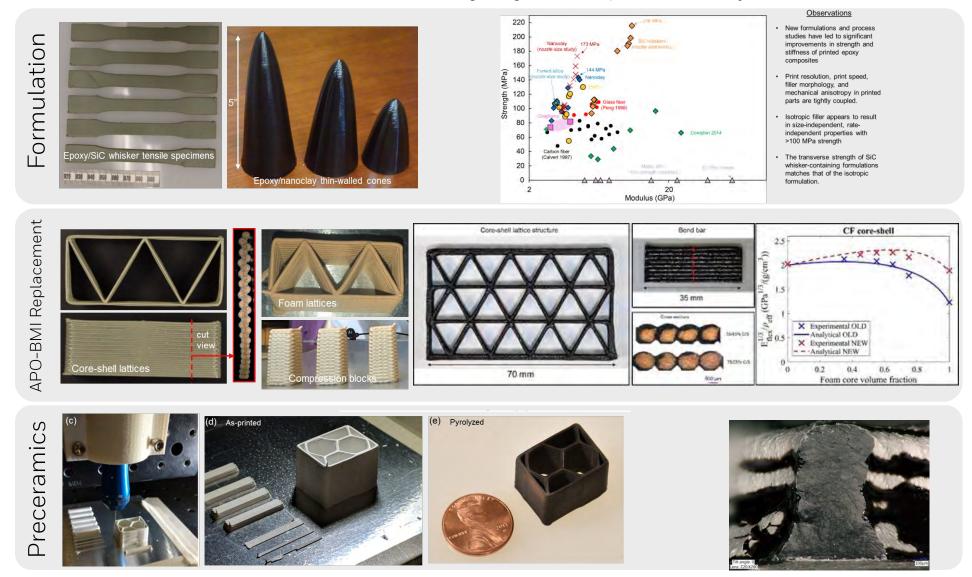
Desire to find replacement materials for rigid syntactic materials Stiffness, load-bearing capability, and tight dimensional tolerance



<u>Thanks to the</u> <u>University of Tennessee</u>

THERMOSET AM: FORMULATION, ENHANCED PROPERTIES, & PRECERAMIC POLYMER RESINS

Materials for Extreme Environments - Targeting Metal Properties with Polymers



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University of Tennessee

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Christopher Williams Clay Arrington Danny Rau Johanna Vandenbrande

Pittsburg State University

Petar Dvornic James Beach

University of Oklahoma Mrinal Saha

University of Texas-El Paso Yirong Lin David Espalin